

MOS FIELD EFFECT TRANSISTOR

2SJ411

P-CHANNEL SIGNAL MOS FET FOR SWITCHING

The 2SJ411 is a P-channel MOS FET of a vertical type and is a switching element that can be directly driven by the output of an IC operating at 5 $\,\mathrm{V}$.

This product has a low ON resistance and superb switching characteristics and is ideal for power control switches and DC/DC converters.

FEATURES

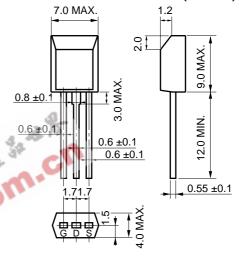
- · Radial taping supported
- · Can be directly driven by 5-V IC
- · Low ON resistance

 $R_{DS(on)} = 0.24 \Omega$ MAX. @VGS = -4 V, $I_D = -2.5$ A

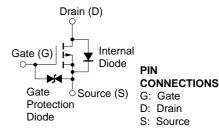
RDS(on) = 0.11 Ω MAX. @Vgs = -10 V, ID = -2.5 A



PACKAGE DIMENSIONS (in mm)



EQUIVALENT CIRCUIT



ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

PARAMETER	SYMBOL	TEST CONDITIONS	RATING	UNIT
Drain to Source Voltage	VDSS	V _G S = 0	-30	V
Gate to Source Voltage	Vgss	V _{DS} = 0	-20/+10	V
Drain Current (DC)	I _{D(DC)}		±5.0	А
Drain Current (Pulse)	ID(pulse)	PW ≤ 10 μs Duty cycle ≤ 1 %	±20.0	А
Total Power Dissipation	Рт1	T _A = 25 °C	1.0	W
Total Power Dissipation	P _{T2}	Tc = 25 °C	6.0	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C

The internal diode connected between the gate and source of this product is to protect the product from static electricity. If the product is used in a circuit where the rated voltage of the product may be exceeded, connect a protection circuit.

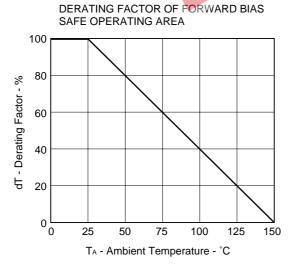
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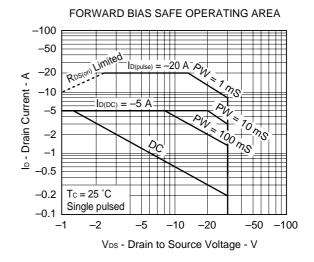


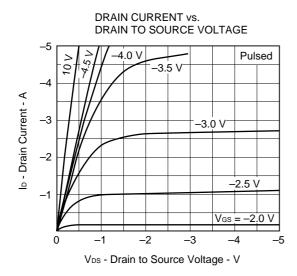
ELECTRICAL CHARACTERISTICS (TA = 25 °C)

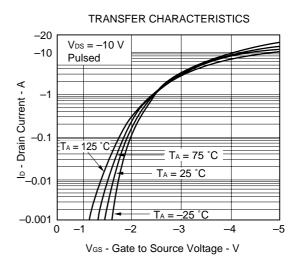
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain Cut-Off Current	IDSS	V _{DS} = -30 V, V _{GS} = 0			-10	μΑ
Gate Leakage Current	Igss	$V_{GS} = -16/+10 \text{ V}, V_{DS} = 0$			±10	μΑ
Gate Cut-Off Voltage	Vgs(off)	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-1.0	-1.4	-2.0	V
Forward Transfer Admittance	yfs	$V_{DS} = -10 \text{ V}, I_{D} = -2.5 \text{ A}$	3.0			S
Drain to Source On-State Resistance	RDS(on)1	Vgs = -4 V, ID = -2.5 A		0.175	0.24	Ω
Drain to Source On-State Resistance	R _{DS(on)2}	V _G S = −10 V, I _D = −2.5 A		0.096	0.11	Ω
Input Capacitance	Ciss	V _{DS} = -10 V, V _{GS} = 0		790		pF
Output Capacitance	Coss	f = 1.0 MHz		580		pF
Reverse Transfer Capacitance	Crss			280		pF
Turn-On Delay Time	td(on)	V _{DD} = −15 V, I _D = −2.5 A		10		ns
Rise Time	tr	$V_{GS(on)} = -10 \text{ V}$		110		ns
Turn-Off Delay Time	td(off)	$R_G = 10 \Omega$, $R_L = 6 \Omega$.0	195		ns
Fall Time	t f		通用	185		ns
Gate Input Charge	Q _G	V _{DS} = -24 V V _{GS} = -10 V		29.8		nC
Gate to Source Charge	Qgs	Vgs = -10 V	1.0	2.7		nC
Gate to Drain Charge	Q _{GD}	$I_D = -5.0 \text{ A, } I_G = -2 \text{ mA}$		11.5		nC
Internal Diode Forward Voltage	V _F (S-D)	IF = 5.0 A, Vgs = 0		1.0		V
Internal Diode Reverse Recovery Time	trr	IF = 5.0 A, VGS = 0		140		ns
Internal Diode Reverse Recovery Charge	Qrr	$di/dt = 50 A/\mu s$		160		nC

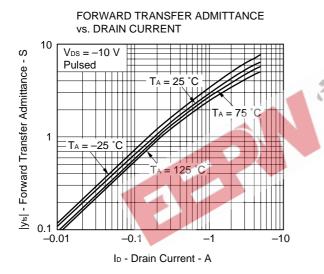
TYPICAL CHARACTERISTICS (TA = 25 °C)

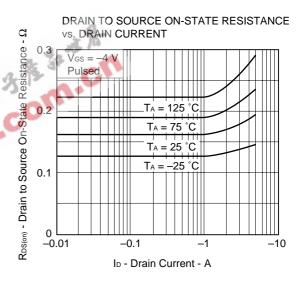


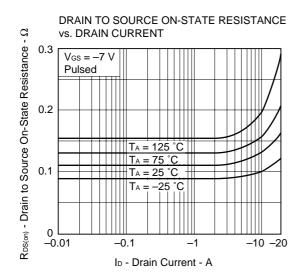


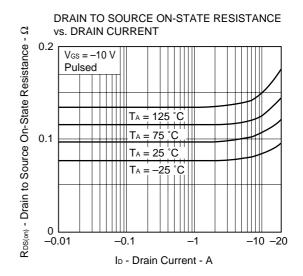


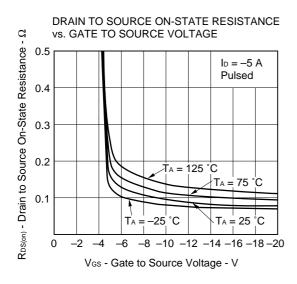


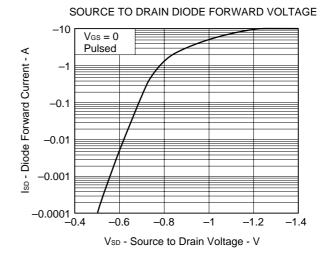


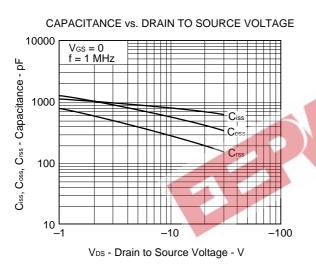


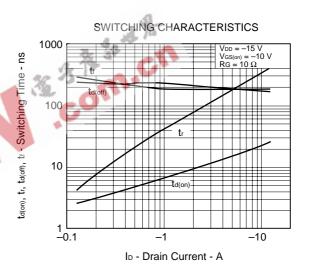


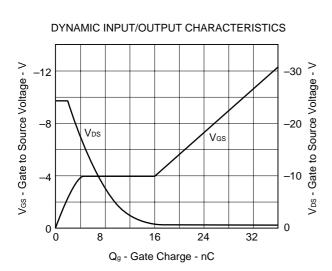


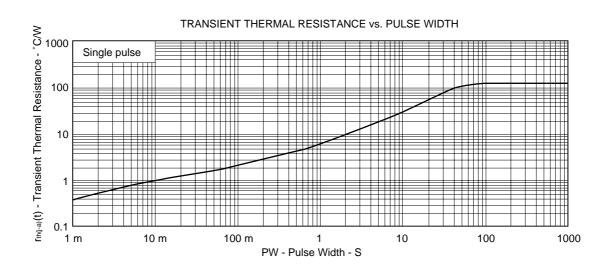












REFERENCE

Document Name	Document No.		
NEC semiconductor device reliability/quality control system	TEI-1202		
Quality grade on NEC semiconductor devices	IEI-1209		
Semiconductor device mounting technology manual	C10535E		
Guide to quality assurance for semiconductor devices	MEI-1202		
Semiconductor selection guide	X10679E		

NEC 2SJ411

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Specific: Aircrafts, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

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Anti-radioactive design is not implemented in this product.

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